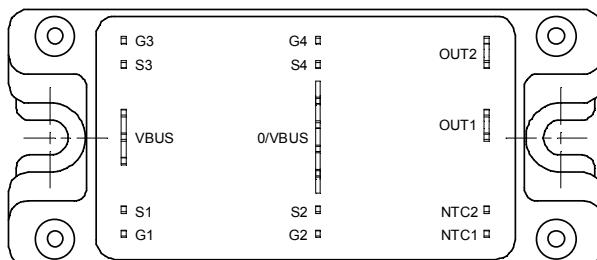
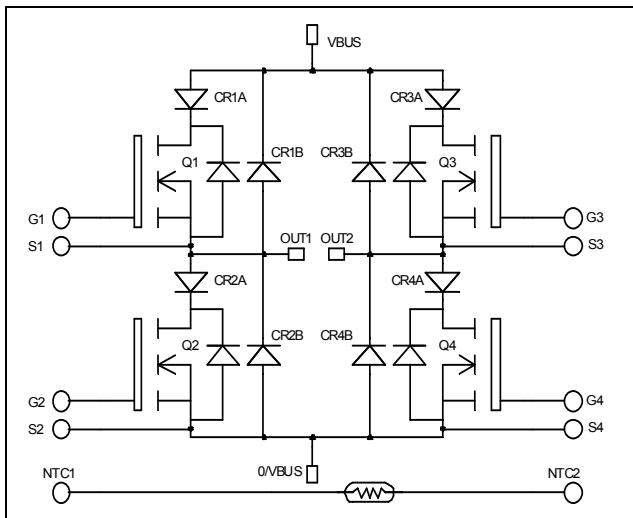


**Full - Bridge  
Series & SiC parallel diodes  
Super Junction  
MOSFET Power Module**



### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
V <sub>DSS</sub>	Drain - Source Breakdown Voltage	800	V
I <sub>D</sub>	Continuous Drain Current	T <sub>c</sub> = 25°C T <sub>c</sub> = 80°C	15 11
I <sub>DM</sub>	Pulsed Drain current		
V <sub>GS</sub>	Gate - Source Voltage	±30	V
R <sub>DSon</sub>	Drain - Source ON Resistance	290	mΩ
P <sub>D</sub>	Maximum Power Dissipation	T <sub>c</sub> = 25°C 156	W
I <sub>AR</sub>	Avalanche current (repetitive and non repetitive)	24	A
E <sub>AR</sub>	Repetitive Avalanche Energy	0.5	mJ
E <sub>AS</sub>	Single Pulse Avalanche Energy	670	

 **CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handing Procedures Should Be Followed.

**V<sub>DSS</sub> = 800V**

**R<sub>DSon</sub> = 290mΩ max @ T<sub>j</sub> = 25°C**

**I<sub>D</sub> = 15A @ T<sub>c</sub> = 25°C**

### Application

- Motor control
- Switched Mode Power Supplies
- Uninterruptible Power Supplies

### Features

- **COOLMOS® Power Semiconductors**
  - Ultra low R<sub>DSon</sub>
  - Low Miller capacitance
  - Ultra low gate charge
  - Avalanche energy rated
- **Parallel SiC Schottky Diode**
  - Zero reverse recovery
  - Zero forward recovery
  - Temperature Independent switching behavior
  - Positive temperature coefficient on VF
- Kelvin source for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

### Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

### Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$\text{BV}_{\text{DSS}}$	Drain - Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	800			V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 800\text{V}$	$T_j = 25^\circ\text{C}$		25	$\mu\text{A}$
		$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 800\text{V}$	$T_j = 125^\circ\text{C}$		250	
$R_{\text{DS(on)}}$	Drain – Source on Resistance	$V_{\text{GS}} = 10\text{V}, I_D = 7.5\text{A}$			290	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_D = 1\text{mA}$	2.1	3	3.9	V
$I_{\text{GSS}}$	Gate – Source Leakage Current	$V_{\text{GS}} = \pm 20\text{ V}, V_{\text{DS}} = 0\text{V}$			$\pm 100$	$\text{nA}$

### Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}} = 0\text{V}$ $V_{\text{DS}} = 25\text{V}$ $f = 1\text{MHz}$		2254		$\text{pF}$
$C_{\text{oss}}$	Output Capacitance			1046		
$C_{\text{rss}}$	Reverse Transfer Capacitance			54		
$Q_g$	Total gate Charge	$V_{\text{GS}} = 10\text{V}$ $V_{\text{Bus}} = 400\text{V}$ $I_D = 15\text{A}$		91		$\text{nC}$
$Q_{\text{gs}}$	Gate – Source Charge			12		
$Q_{\text{gd}}$	Gate – Drain Charge			46		
$T_{\text{d(on)}}$	Turn-on Delay Time	<b>Inductive switching @ 125°C</b> $V_{\text{GS}} = 15\text{V}$ $V_{\text{Bus}} = 533\text{V}$ $I_D = 15\text{A}$		10		$\text{ns}$
$T_r$	Rise Time			13		
$T_{\text{d(off)}}$	Turn-off Delay Time			83		
$T_f$	Fall Time			35		
$E_{\text{on}}$	Turn-on Switching Energy	<b>Inductive switching @ 25°C</b> $V_{\text{GS}} = 15\text{V}, V_{\text{Bus}} = 533\text{V}$ $I_D = 15\text{A}, R_G = 5\Omega$		146		$\mu\text{J}$
$E_{\text{off}}$	Turn-off Switching Energy ①			139		
$E_{\text{on}}$	Turn-on Switching Energy	<b>Inductive switching @ 125°C</b> $V_{\text{GS}} = 15\text{V}, V_{\text{Bus}} = 533\text{V}$ $I_D = 15\text{A}, R_G = 5\Omega$		255		$\mu\text{J}$
$E_{\text{off}}$	Turn-off Switching Energy ①			171		

### Series diode ratings and characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{\text{F(AV)}}$	Maximum Average Forward Current	50% duty cycle		30		A
$V_F$	Diode Forward Voltage	$I_F = 30\text{A}$		1.1	1.15	V
		$I_F = 60\text{A}$		1.4		
		$I_F = 30\text{A}$	$T_j = 125^\circ\text{C}$	0.9		
$t_{\text{rr}}$	Reverse Recovery Time	$I_F = 30\text{A}$	$T_j = 25^\circ\text{C}$	24		ns
		$V_R = 133\text{V}$	$T_j = 125^\circ\text{C}$	48		
$Q_{\text{rr}}$	Reverse Recovery Charge	$I_F = 30\text{A}$	$T_j = 25^\circ\text{C}$	33		$\text{nC}$
		$V_R = 133\text{V}$	$T_j = 125^\circ\text{C}$	150		

① In accordance with JEDEC standard JESD24-1.

**Parallel diode ratings and characteristics**

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
I <sub>F(AV)</sub>	Maximum Average Forward Current	50% duty cycle	T <sub>c</sub> = 125°C		5		A
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> = 5A	T <sub>j</sub> = 25°C		1.6	1.8	V
			T <sub>j</sub> = 175°C		2.6	3.0	
Q <sub>C</sub>	Total Capacitive Charge	I <sub>F</sub> = 5A, V <sub>R</sub> = 600V di/dt = 500A/μs			14		nC
Q	Total Capacitance	f = 1MHz, V <sub>R</sub> = 200V			45		pF
		f = 1MHz, V <sub>R</sub> = 400V			33		

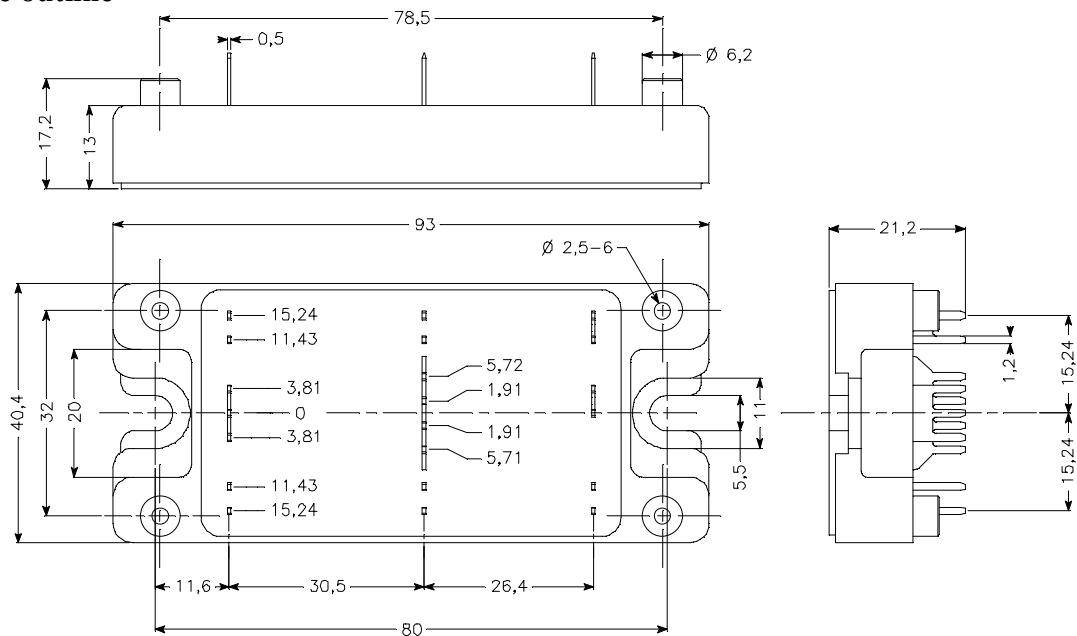
**Thermal and package characteristics**

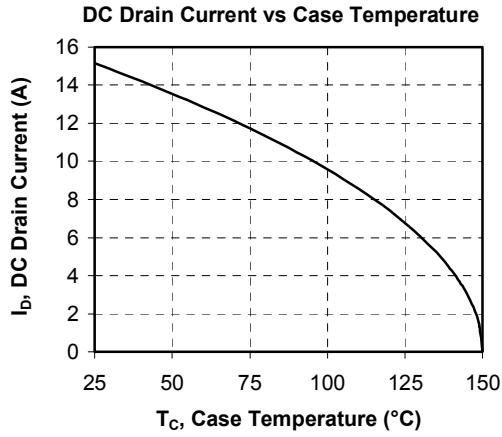
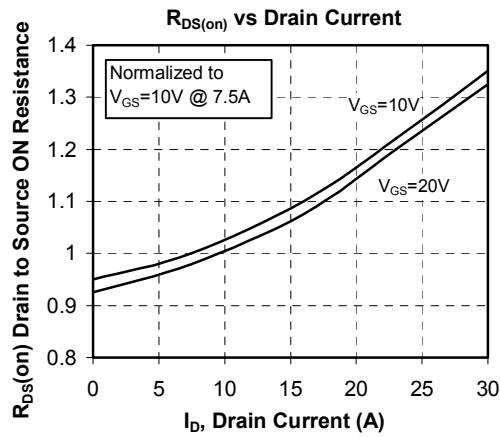
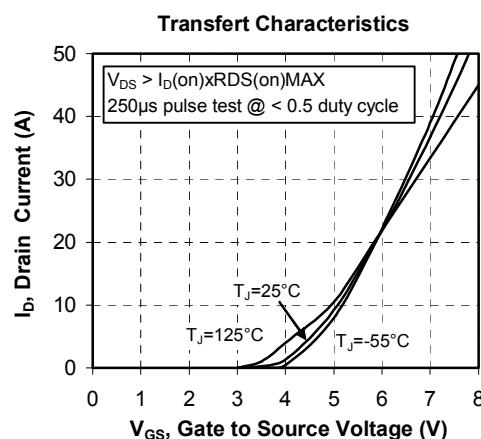
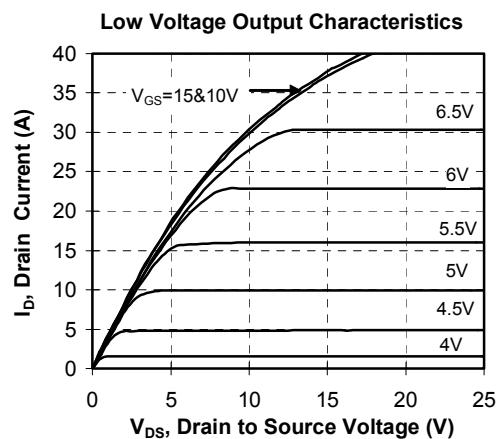
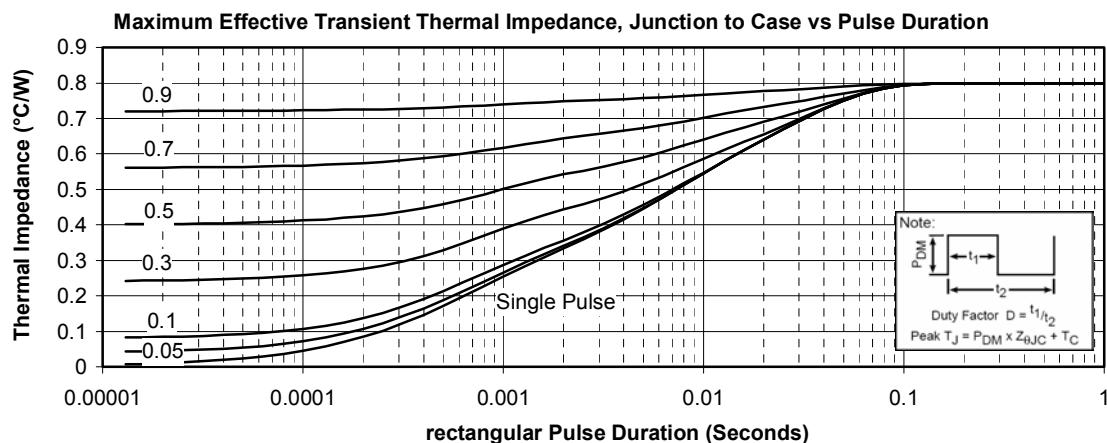
<i>Symbol</i>	<i>Characteristic</i>	<i>Transistor</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R <sub>thJC</sub>	Junction to Case	Transistor			0.8	°C/W
		Series diode			1.2	
		Parallel diode			2.5	
V <sub>ISOL</sub>	RMS Isolation Voltage, any terminal to case t=1 min, I <sub>isol</sub> <1mA, 50/60Hz	2500				V
T <sub>J</sub>	Operating junction temperature range	-40		150		°C
T <sub>STG</sub>	Storage Temperature Range	-40		125		
T <sub>C</sub>	Operating Case Temperature	-40		100		
Torque	Mounting torque	To Heatsink	M5		4.7	N.m
Wt	Package Weight				160	g

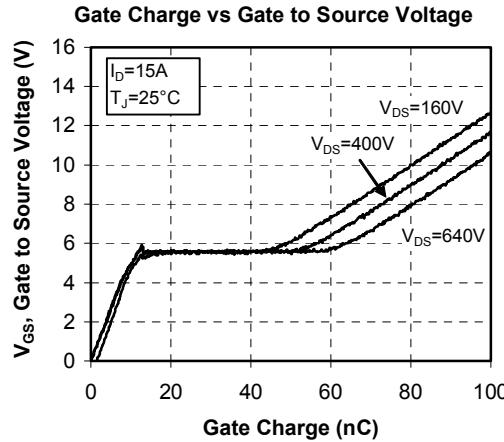
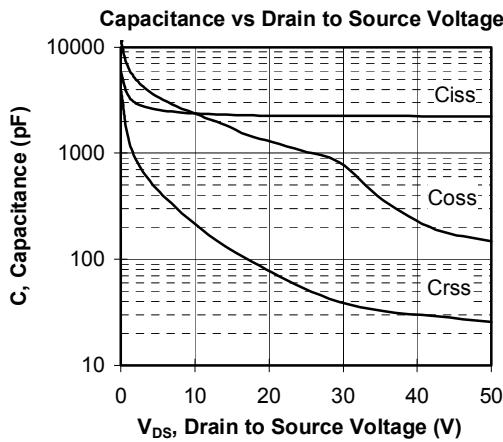
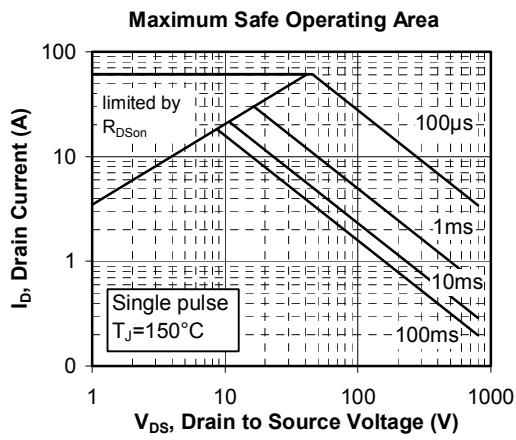
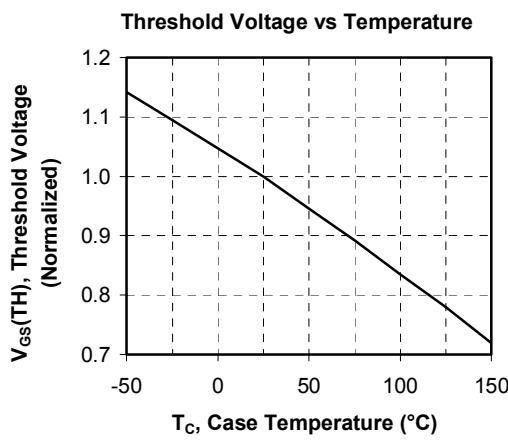
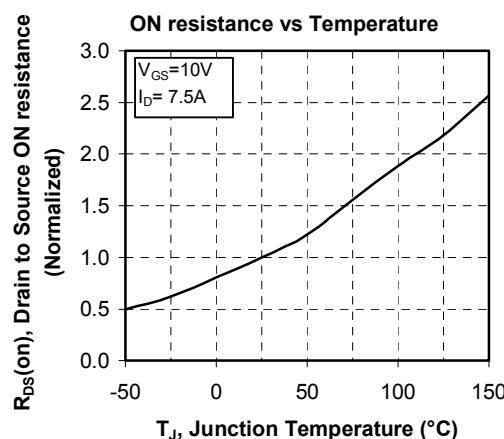
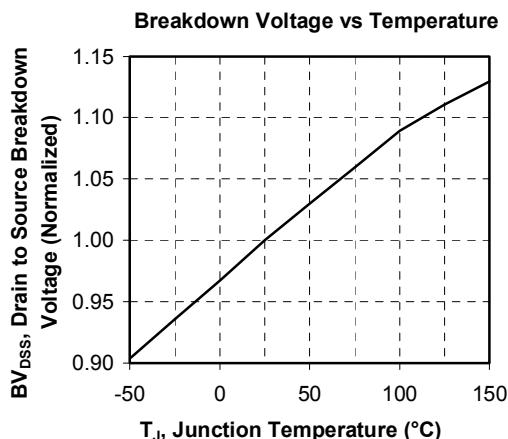
**Temperature sensor NTC**

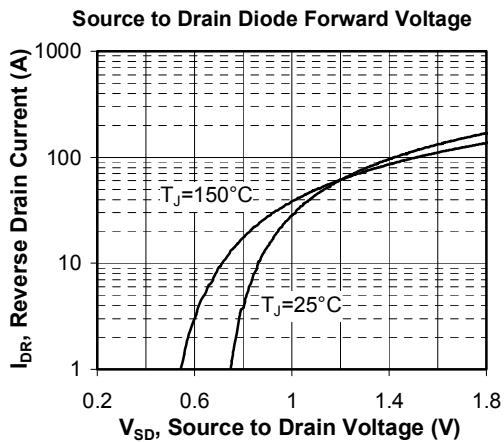
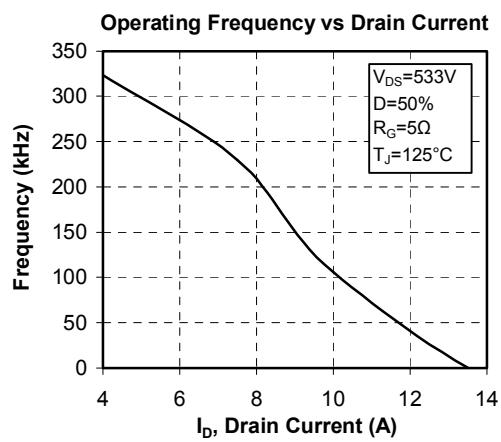
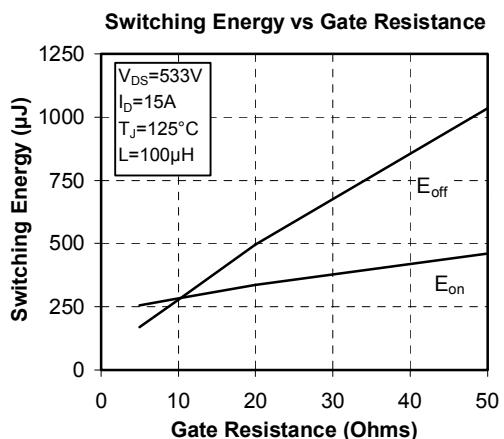
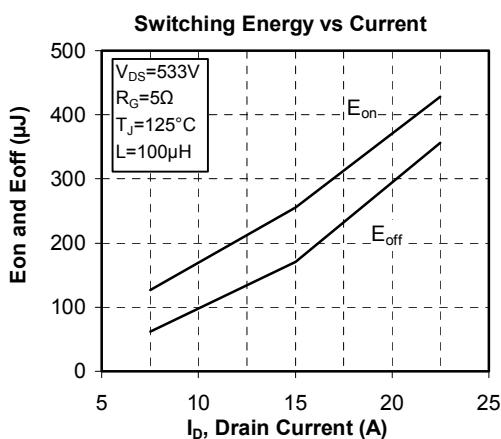
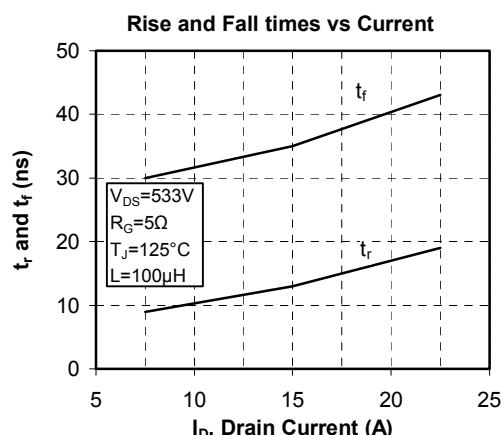
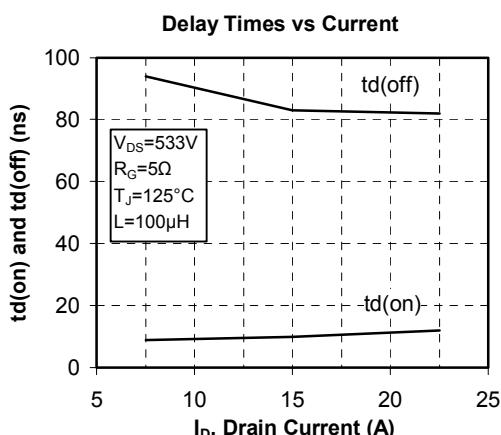
<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R <sub>25</sub>	Resistance @ 25°C		68		kΩ
B <sub>25/85</sub>	T <sub>25</sub> = 298.16 K		4080		K

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]} \quad T: \text{Thermistor temperature} \\ R_T: \text{Thermistor value at } T$$

**Package outline**


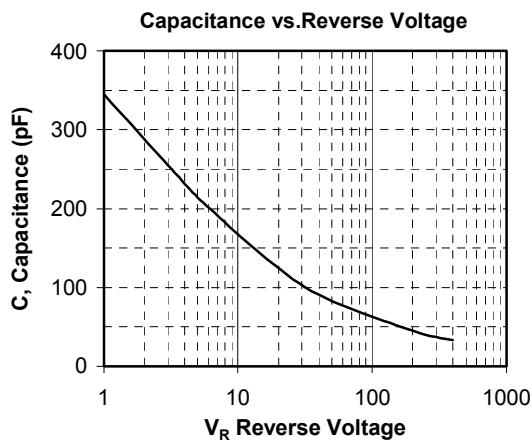
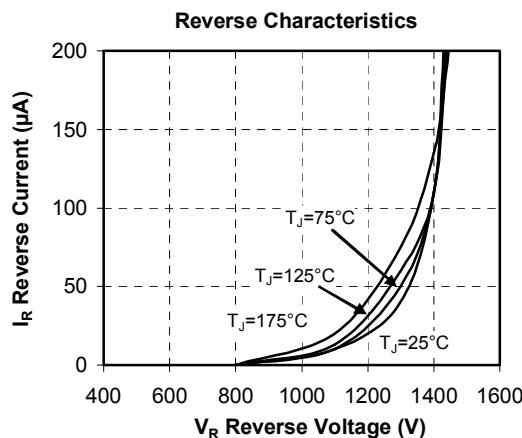
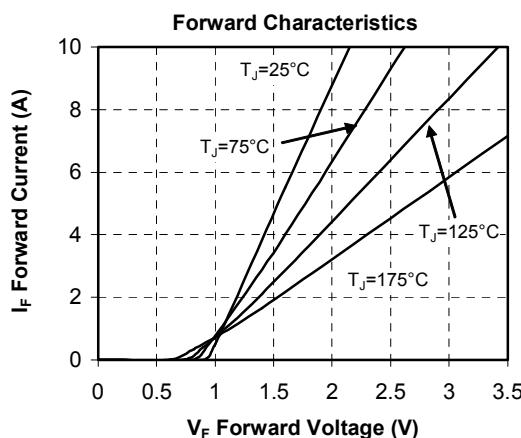
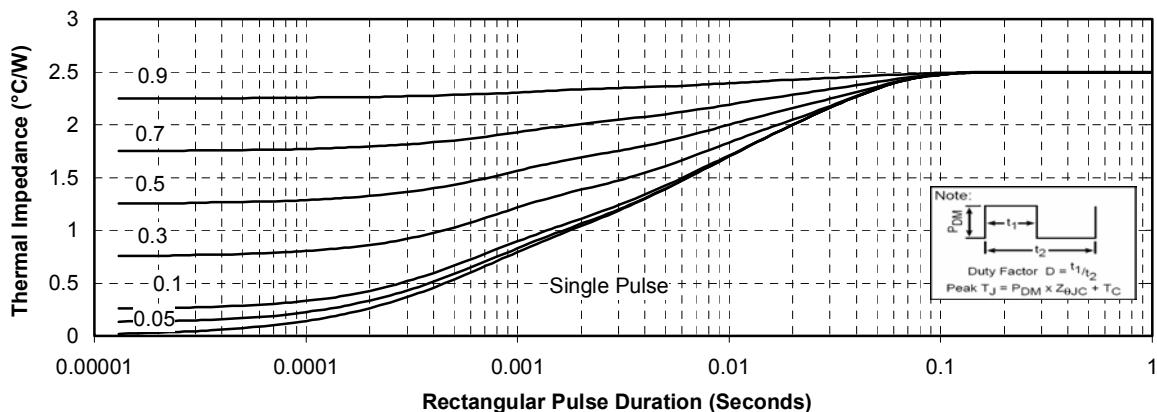
**Typical CoolMOS Performance Curve**






### Typical SiC Diode Performance Curve

Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration



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